

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2704272

SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>HAN MENG @EUGENE LEE LEE</td> <td>01/17/2014</td> </tr> <tr> <td>ANIS FAUZI BIN ABDUL AZIZ</td> <td>01/20/2014</td> </tr> <tr> <td>KHOO YIEN SIEN</td> <td>01/08/2014</td> </tr> </tbody> </table>		Name	Execution Date	HAN MENG @EUGENE LEE LEE	01/17/2014	ANIS FAUZI BIN ABDUL AZIZ	01/20/2014	KHOO YIEN SIEN	01/08/2014
Name	Execution Date								
HAN MENG @EUGENE LEE LEE	01/17/2014								
ANIS FAUZI BIN ABDUL AZIZ	01/20/2014								
KHOO YIEN SIEN	01/08/2014								
RECEIVING PARTY DATA									
Name:	TEXAS INSTRUMENTS INCORPORATED								
Street Address:	P. O. BOX 655474								
Internal Address:	MS 3999								
City:	DALLAS								
State/Country:	TEXAS								
Postal Code:	75265-5474								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14167647</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14167647				
Property Type	Number								
Application Number:	14167647								
CORRESPONDENCE DATA									
Fax Number:	(214)479-1273								
Phone:	214-479-1156								
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ATTORNEY DOCKET NUMBER:	TI-73520								
NAME OF SUBMITTER:	JACKIE MCBRIDE								
Signature:	/Jackie McBride/								

Date:

01/29/2014

Total Attachments: 2

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Application No.

Docket No. TI-73520

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made.

WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, with a place of business at 12500 TI Boulevard M/S 3999, Dallas, Texas 75243, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon, as well as to U.S. Provisional Application No(s). 6XXXXXXX filed XXXXXX, 2012.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign unto the said TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my entire right, title and interest in and to the said invention and in and to the said application(s) and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Patent and Trademark Office to issue all patents for said invention, or patents resulting therefrom, to the said TEXAS INSTRUMENTS INCORPORATED, as assignee of my entire right, title and interest.


I also hereby sell and assign to TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my corresponding rights to the invention disclosed in said application in all other countries of the world, including the right to claim priority, file applications and obtain patents under the terms of the Paris Convention for the Protection of Industrial Property, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such rights.

I hereby further agree that I will communicate to said TEXAS INSTRUMENTS INCORPORATED, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TEXAS INSTRUMENTS INCORPORATED, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

I authorize the later insertion of the nonprovisional application number and filing date hereinbelow.

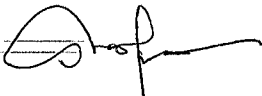
IN WITNESS WHEREOF, I hereunto set hand and seal this day and year;

TITLE	STACKED SEMICONDUCTOR SYSTEM HAVING INTERPOSER OF HALF-ETCHED AND MOLDED SHEET METAL		
NONPROVISIONAL APPLICATION NO.		FILING DATE	


SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Lee Han Meng@Eugene Lee
DATE	17 January 2014
RESIDENCE (CITY AND STATE)	Johor, Malaysia

TI-7

TITLE	STACKED SEMICONDUCTOR SYSTEM HAVING INTERPOSER OF HALF-ETCHED AND MOLDED SHEET METAL		
NONPROVISIONAL APPLICATION NO.		FILING DATE	

SIGNATURE OF INVENTOR			
PRINTED NAME OF INVENTOR	Anis Fauzi bin Abdul Aziz		
DATE	20 JANUARY 2014		
RESIDENCE (CITY AND STATE)	Melaka, Malaysia		

TITLE	STACKED SEMICONDUCTOR SYSTEM HAVING INTERPOSER OF HALF-ETCHED AND MOLDED SHEET METAL		
NONPROVISIONAL APPLICATION NO.		FILING DATE	

SIGNATURE OF INVENTOR			
PRINTED NAME OF INVENTOR	Khoo Yien Sien		
DATE	08 Jan 2014		
RESIDENCE (CITY AND STATE)	Melaka, Malaysia		

After recording, return Assignment to:

Texas Instruments Incorporated
 PO Box 655474, M/S 3999
 Dallas, TX 75265

RECORDED: 01/29/2014

PATENT
REEL: 032083 FRAME: 0599